





(4) CONTACTS IN ROWS A,C,E,G,J,K,M,P,R AND T ARE SINGLE BEAM CONTACTS, TYPICALLY USED AS GROUND PINS. (NOTE: CONTACTS IN ROWS J & K ARE TIED TOGETHER [COMMONED])

SHPERICAL SHAPE DUE TO REFLOW ATTACHMENT.

(3) MATED HEIGHT EFFECTED BY CUSTOMERS'

PROFILE & SOLDER PASTE.

PCB PAD SIZE, PLATING, SOLDER REFLOW

CONTACTS IN ROWS B, D, F, H, L, N, Q AND S ARE DUAL BEAM CONTACTS, TYPICALLY USED AS SIGNAL PINS.

- FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033. LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEADFREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.
- THIS PRODUCT MEETS THE EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008. PRODUCT MEETING THIS DIRECTIVE IS INDENTIFIED IN THE CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSTION.

spec ref	*			dr Bill Lin		2010/02/02		projection		00.00		s i z e	scale		
tolerance std				eng	e n g Nickor Zuo		2011/06/09	⊕-□		[]	nM	A 4	11:10	11:10	
ASME YI4.5	TOLERANCES UNLESS OTHERWISE SPECIFIED		chr Alex Cao		2011/06/24				•	-	ecn no	ELX-DG-0	ELX-DG-003943-1		
-	OTHERWISE STECTIFED			appr Pei-Ming Zheng			2011/06/27	product family		GΙ	G-Array	rel level	Rele	Released	
surface 🗸	linear	0.X	±0.30	FCi		Ψ CIC Annau					0 0			rev	
		0.XX	±0.10		— GIG-Array				0		55740				
		0.XXX	±0.05	1		+ 5mm	n RECP. ASS	Y. 200 SIG.	POS.	. 💆				G	
=	anaular	0°	+2°	www	fci.com	cat. no) .	*	Proc	duct -	Customer	Drw	sheet 5 of	5	

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Pro/E File - REV C - 2009-06-09